Form <b>PTO-1595</b> (Rev. 06/ 04) OMB No. 0651-0027 (exp. 6/30/2005)	U.S. DEPARTMENT OF COMMERCE United States Patent and Trademark Office
To the Director of the U.S. Patent and Trademark Office: Please	record the attached documents or the new address(es) below.
1. Name of conveying party(les)/Execution Date(s):  Junichi Nakamura  / 0 - 5 - 0 4  Execution Dates: September 22, 2004  Additional name(s) of conveying party(les) attached? Yes x No  3. Nature of Conveyance:  x Assignment Merger  Security Agreement Change of Name  Government Interest Assignment  Executive Order 9424, Confirmatory License  Other	2. Name and address of receiving party(ies)  Name: Micron Technology, Inc.  Internal Address: Street Address:  8000 S. Federal Way  City: Boise  State: Idaho  Country: United States of America Zip: 83707-0006  Additional name(s) & address(es) Yes X No attached:
4. Application or patent number(s):  A. Patent Application No.(s)  Additional numbers attached?	This document is being filed together with a new application.  B. Patent No.(s)  / 0/957724  Yes x No
5. Name and address to whom correspondence concerning document should be mailed:  Name: Thomas J. D'Amico DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP  Internal Address: Atty. Dkt.: M4065.1092/P1092  Street Address: 2101 L Street NW	6. Total number of applications and patents involved:  7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  X Authorized to be charged by credit card  Authorized to be charged to deposit account  Enclosed  None required (government interest not affecting title)
City:         Washington           State:         DC         Zip: _20037-1526           Phone Number:         (202) 828-2232           Fax Number:         (202) 887-0689           Fmail Address:         DAmicoT@DSMO.com	8. Payment Information:  a. Credit Card Last 4 Numbers 1008 Expiration Date 02/28/06  b. Deposit Account Number Authorized User Name

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Thomas J. D'Amico - 28,371

Name of Person Signing

9. Signature.

October 5, 2004 Date

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Total number of pages including cover sheet, attachments, and documents:

## ASSIGNMENT AND AGREEMENT

For value received, I, Junichi Nakamura, hereby sell, assign and transfer to Micron Technology, Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled IMAGE SENSOR WITH ON-CHIP SEMI-COLUMN-PARALLEL PIPLINE ADCS, described in an application for Letters Patent of the United States, executed by me of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

1820909 v1; 1310T01!.DOC

PATENT REEL: 015873 FRAME: 0679

I agree that, when requested, I shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

**	Junichi Nakamura					
Date: SEF	2 2 2004		£ a			
Japan		)				
City of Tokyo	NITED STATES OF AM	)ss.:				
Embassy of the	NITED STATES OF AM	ERICA)				
United States of						
America _		)				
On this	day of	SEP 2 2 2004	,	, before me		
personally came	Junichi Nakamura		, to me kne	, to me known to be the individual		
described in and w	ho executed the	e foregoing instr	ument, and acknow	wledged execution		
of the same.						
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				<del>lotary Pub</del> lic		

Paul J. Herman American Vice Consul

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For value received, I, Junichi Nakamura, hereby sell, assign and transfer to Micron Technology, Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled IMAGE SENSOR WITH ON-CHIP SEMI-COLUMN-PARALLEL PIPLINE ADCS, described in an application for Letters Patent of the United States, executed by me of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

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1820909 v1; 1310T01!.DOC

PATENT REEL: 015873 FRAME: 0681

I agree that, when requested, I shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

			Tur	Jan Jan Chinichi Nakamu	nekamura
Date: SEF	2 2 2004		3 00	, .	
Japan		)			
City of Tokyo  JAPAN  CITY OF TOKYO		)ss.:			
Embassy of the	NITED STATES OF AM	IERICA)			
United States of					
America		)			
On this	day of	SEP 2 2	2004	,	, before me
personally came	Junichi Nakamura		, to me known to be the individual		
described in and w	ho executed th	e foregoing	instrume	ent, and ackno	wledged execution
of the same.					
			<u></u>	Jaug	11
					<del>Notary Pub</del> lic

Paul J. Herman American Vice Consul

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**PATENT** REEL: 015873 FRAME: 0682

**RECORDED: 10/05/2004**